

FEATURES

- LVDS Output logic
- Wide frequency Range 100MHz to 250MHz
- Low phase RMS jitter 50fs [12kHz - 20MHz]
- Supply voltage range 1.8V 2.5V, 3.3Volts
- Tristate function to conserve power



('536' package displayed)



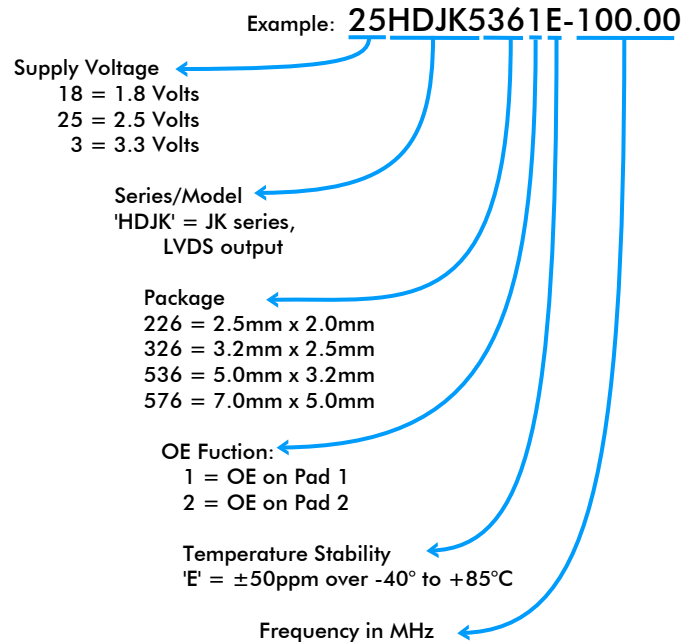
DESCRIPTION

'HDJK' series oscillators have been developed as a precision frequency control component with a short lead time, providing a LVDS output clock oscillator with low current consumption, wide operating frequency range and an integrated RMS phase jitter performance of 50fs r.m.s. Available in 4 industry-standard ceramic packages, 7 x 5mm, 5 x 3.2mm, 3.2 x 2.5mm and 2.5 x 2.0mm SMD.

GENERAL SPECIFICATION

Output Logic Type:	LVDS
Frequency Range:	
1.8V:	100MHz ~ 175MHz
2.5/3.3V:	100MHz ~ 250MHz
Load:	LVDS standard 100Ω differential
Power Supply Voltage:	1.8±5%VDC, 2.5±10%VDC or +3.3±10%VDC
Differential Output Voltage:	Hi: 1.4V typ. 1.6 max. Lo: 1.1V typ. 0.9 V min.
Frequency Stability:	See Stability Table
Storage Temperature:	-55°C tp +150°C
Output Swing (single-end):	200mV minimum
Duty Cycle:	50%±5%
Rise Time:	0.15 nsec typical**
Fall Time:	0.3 nsec maximum**
Current Consumption:	22mA typical, 30mA maximum
Current with output disabled:	30uA maximum
Start-up Time:	1.0ms typical, 5.0ms maximum
Ageing:	±3ppm max. first year, ±2ppm max. per year thereafter
OE Control on Pad 1	
Enable:	70% V _{DD} min., or no connection
Disable:	30%V _{DD} max., (high impedance).
Output Enable Time:	10ms max.
Output Disable Time:	0.2us max.
Phase Jitter r.m.s.:	50fsec typ., 300fsec max.

PART NUMBERING



HDJK SERIES PHASE NOISE & PHASE JITTER DATA

SSB Phase Noise Data (dBc/Hz typical)	Frequency (MHz)	125.00	156.25
	100Hz offset	-114	-108
	1kHz offset	-135	-132
	10kHz offset	-147	-141
	100kHz offset	-157	-152
	1MHz offset	-163	-160
	10MHz offset	-164	-161

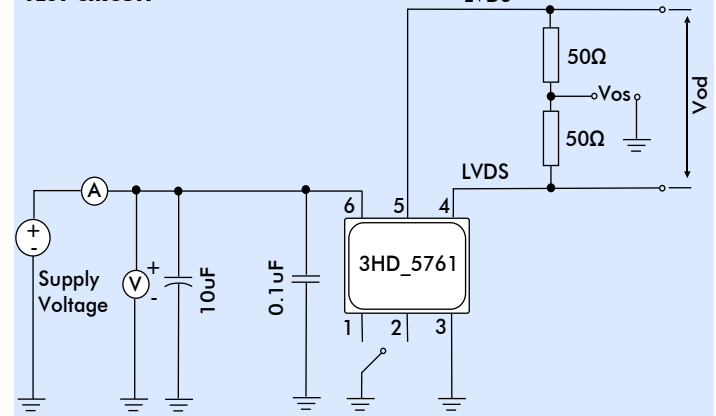
STABILITY OVER TEMPERATURE RANGE

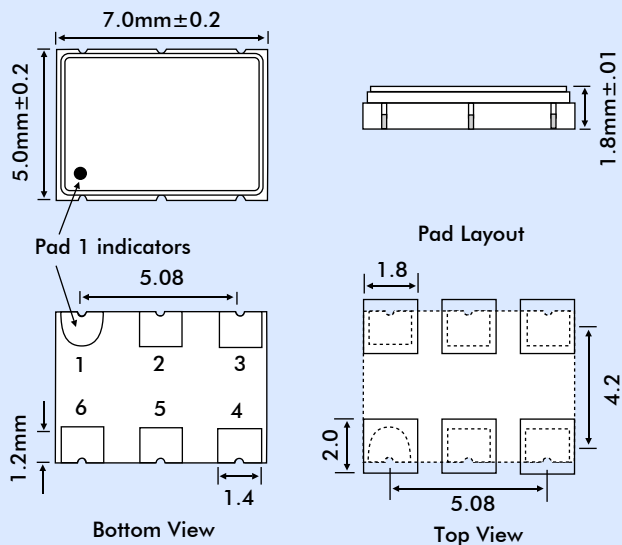
Stability ±ppm	Temperature Range °C	Order Code
25	-10 to +70	A
50	-10 to +70	B
100	-10 to +70	C
25	-40 to +85	D
50	-40 to +85	E
100	-40 to +85	F

Notes:

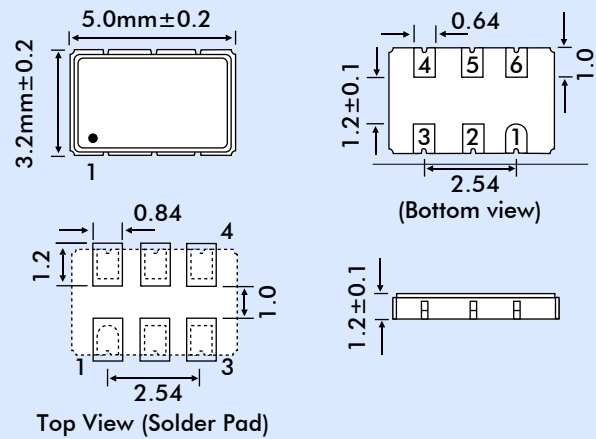
- * Stability code for ±50ppm over -40° to +85°C is 'E.'
- * Note that Frequency stability quoted is inclusive of all conditions, Calibration Tolerance at 25°C, stability over operating temperature range, 1st year ageing at 25°C, supply voltage & output load changes and shock & vibration.
- ** Rise/Fall times are measure between 20% to 80%V_{DD}

TEST CIRCUIT

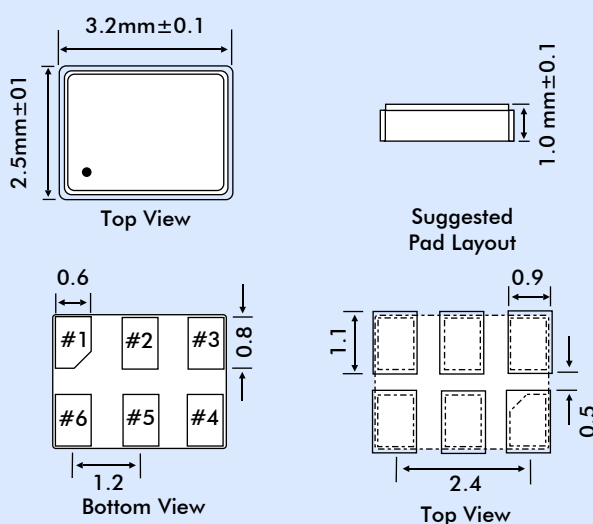


OUTLINE & DIMENSIONS
7.0 x 5.0mm SMD Package

Pad Connections

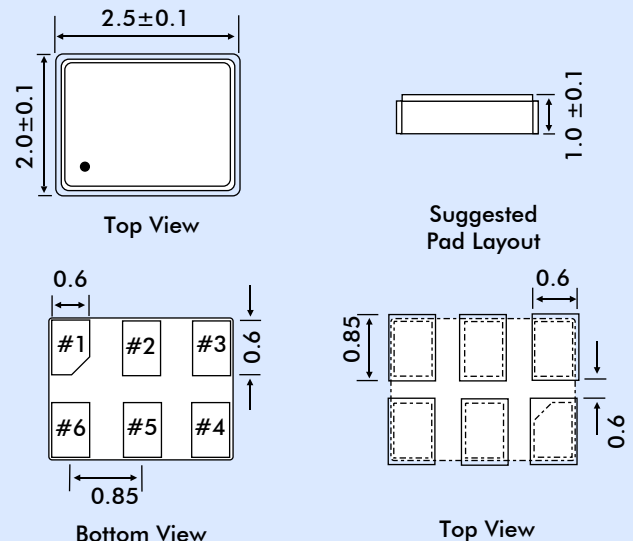
- 1 OE High Enable
- 2 No connection
- 3 Ground
- 4 Output
- 5 Complimentary
- 6 Supply Voltage

5.0 x 3.2mm SMD Package

Pad Connections

- 1 OE High Enable
- 2 No connection
- 3 Ground
- 4 Output
- 5 Complimentary
- 6 Supply Voltage

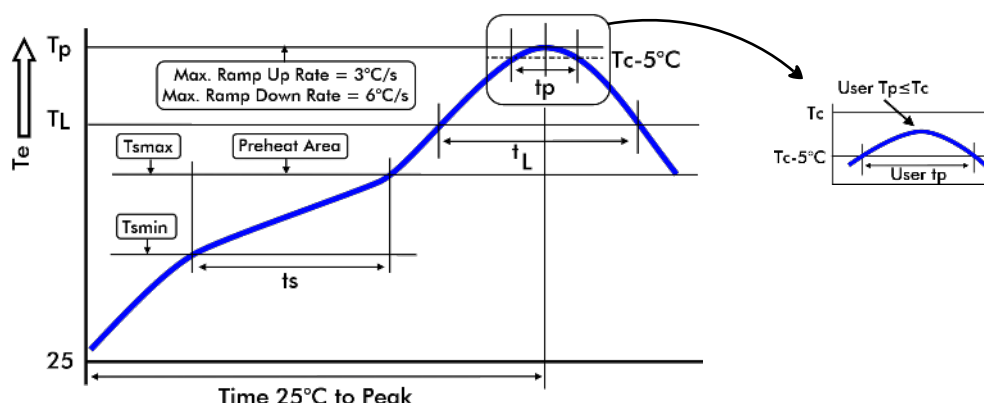
3.2 x 2.5mm SMD Package

Pad Connections

- 1 OE
- 2 No connection
- 3 Ground
- 4 Output
- 5 Complimentary Output
- 6 Supply Voltage

2.5 x 2.0mm SMD Package

Pad Connections

- 1 Voltage Control
- 2 OE
- 3 Ground
- 4 Output
- 5 No connection
- 6 Supply Voltage

Suggested Reflow Profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak		
- Temperature min. (T_s min.)	100°C	150°C
- Temperature max. (T_s max.)	150°C	200°
- Time (t_s) (T_s min. to T_s max.)	60 to 120 seconds	60 to 180 seconds
Ramp-up Rate (T_l to T_p)	3°C/second max.	3°C/second max.
Liquidous temperature (T_l)	183°C	217°C
Time (t_l) maintained above T_l	60 to 150 seconds	60 to 150 seconds
Peak package body temperature (T_p)	235°C	260°C
Time (T_p) within 5°C of the classification temperature T_c	10 to 30 seconds	20 to 40 seconds
Ramp-down rate (T_p to T_l)	6°C/second max.	6°C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

Environmental Approvals	RoHS Compliant, Pb (lead) free in accordance with EU Directive 2002/95/EC 6/6 (2002/95EC) and WEEE (2002/96/EC). Free of halide, cadmium, hexavalent chromium, lead, mercury, PBBs and PBDEs
Moisture sensitivity Level	Level 1 (infinite) according to IPC/JEDEC J-STF-020D.1
Second Level Interconnect	'e4
Storage Temperature Range	-55° to +125°C
Humidity	85%RH, 85°C, 48 hours
Fine Leak / Gross Leak	MIL-STD-202F Method 1014, Cond. A / MIL-STD-883, Method 1014, Cond C.
Solderability	MIL-STD-202F method 208E
Reflow	260°C for 10s. 2 times
Vibration	MIL-STD-202F Method 204, 35g, 50 to 2000Hz
Shock	MIL-STD-202F, Method 213B, Test Cond. E, 1000gg 1/2 sine wave.
Resistance to Solvents	MIL-STD-202, Method 215
Temperature Cyscling	MIL-STD-883, Method 1010
ESD Rating	Human Body Model (HBM): 1500 V minimum.
Pad Surface Finish	Gold (Au)(0.3µm ot 1.0µm) over nickel (Ni)(1.27µm to 8.89µm)
Weight of the Device	576 package: 0.18gm typical, 536 package: 0.09gm typical.